

## FYLS – 5050RGB

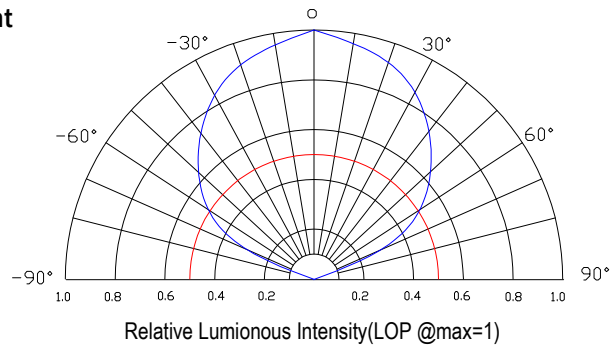
### Radiation pattern.

#### Features:

- Compatible with automatic placement equipment
- Compatible with reflow solder process.

#### Applications:

- Automotive-Telecommunication
- Indicators
- LCD Back-lights
- Illuminations



#### Descriptions:

- Dice material: InGaN.
- Emitting Color: White
- Lens Color: Yellow Diffused.

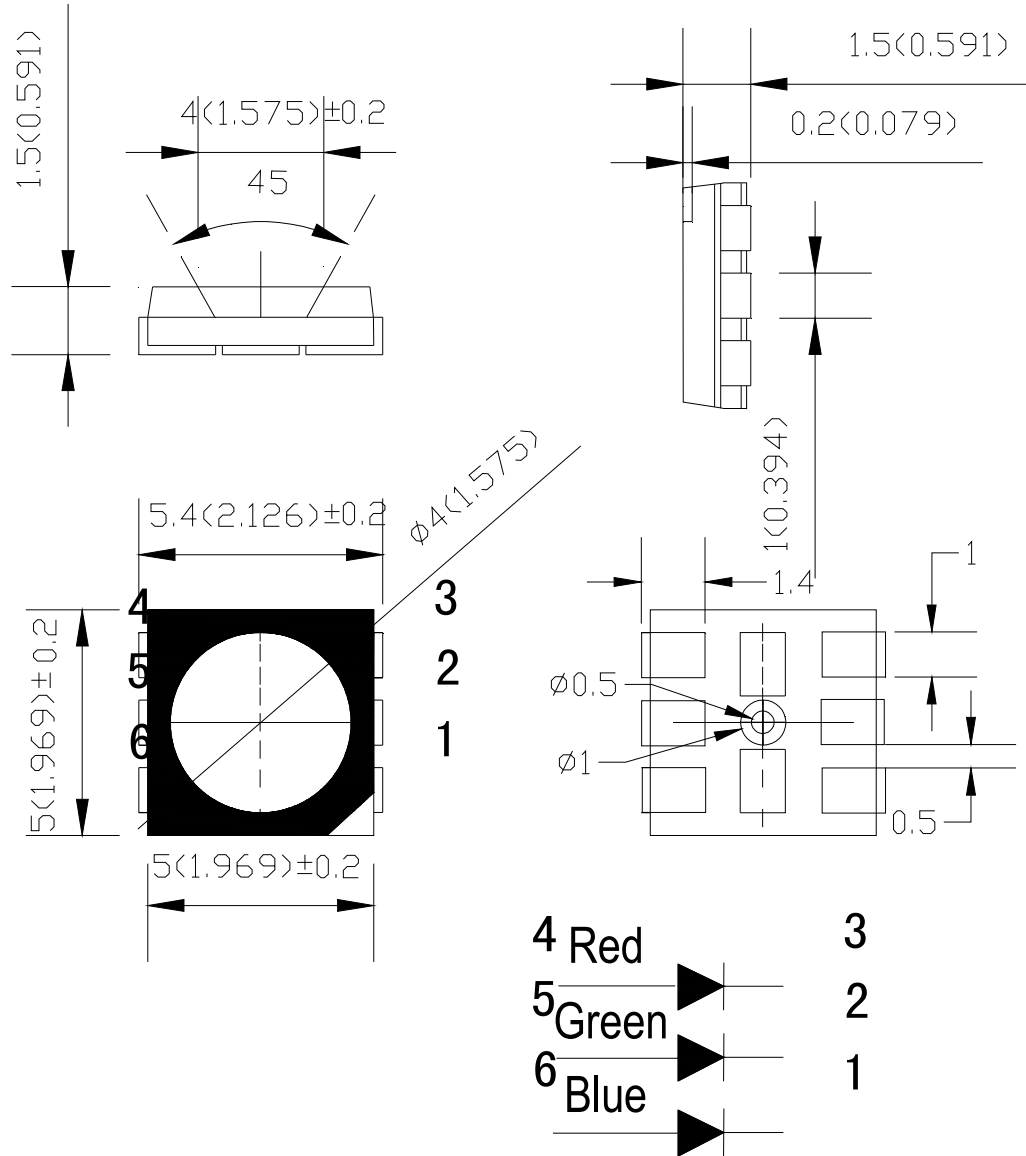
#### Absolute maximum ratings(Ta=25 °c)

Parameter	MAX.		Unit
	Power Dissipation	R	
G		75	
B		75	
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse)	100		mA
Continuous Forward Current	300		mA
Derating Linear From 25°C	0.4		mA/°C
Operating Temperature Range	-30°C to +80°C		
Storage Temperature Range	-40°C to +100°C		
Lead Soldering Temperature[4mm(.157") From Body]	260°C for 5 Seconds		

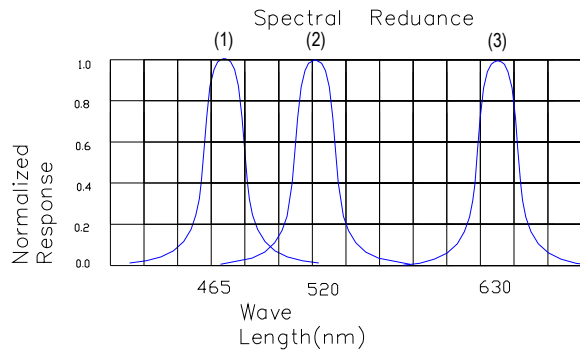
#### Electrical and optical characteristics(Ta=25 °c)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	IV	-	R: 600 G: 1300 B: 400	-	mcd	IF=20mA
Viewing Angle	2θ1/2	-	120	-	Deg	
Wavelength	λd	R:620		R:630	nm	
		G:520		G:525		
		B:465		B:470		
Forward Voltage	VF	3.0	R: 2.2 G: 3.2 B: 3.2	-	V	
Reverse Current	IR			5	μA	VR=5V

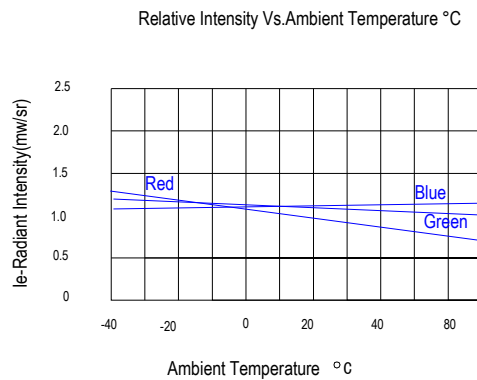
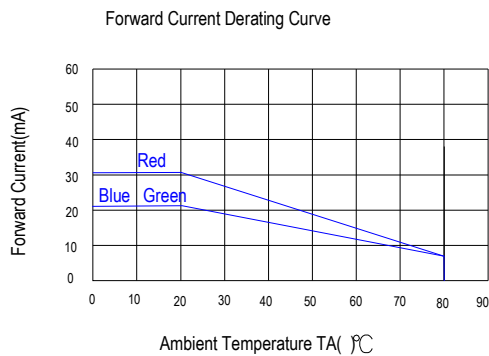
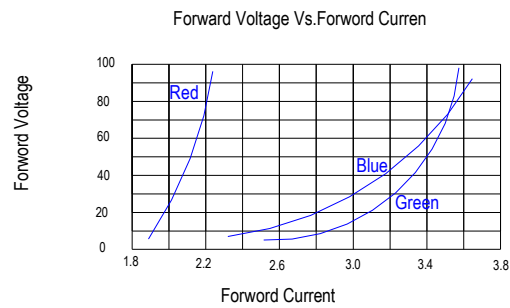
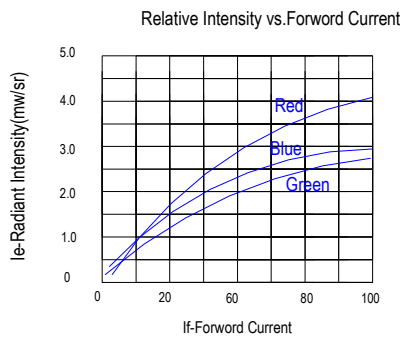
**Package Dimensions**



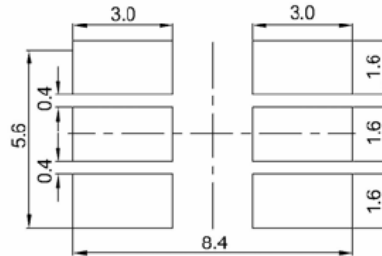
**Typical Electrical Characteristics Curves  
(25 °c Ambient Temperature Unless Otherwise Noted)**



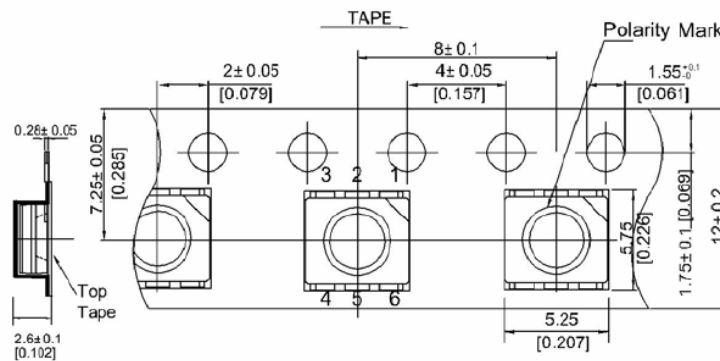
(1) peak@465nm/Blue  
(2) peak@520nm/Pure Green  
(3) peak@630nm/Red



## Recommended Soldering Pattern (Units : mm)

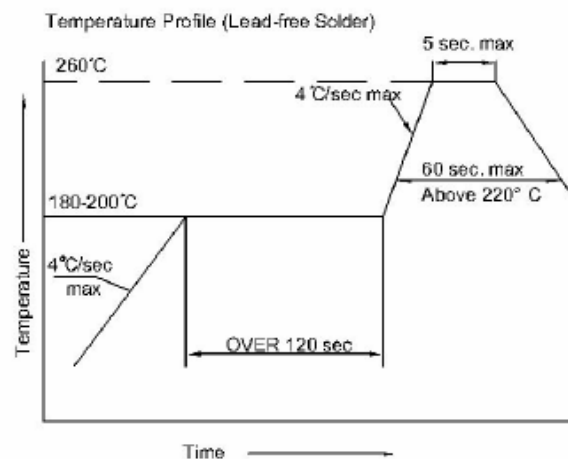
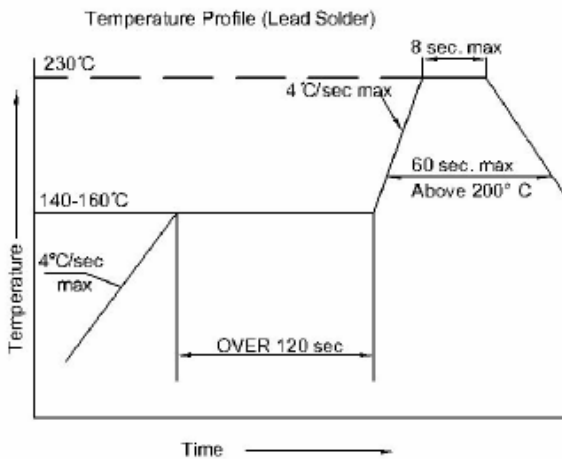


## Tape Specifications (Units : mm)



## SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



◆ **Packing and Shipping Spec.**

